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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Obsolete
Core Processor	ST7
Core Size	8-Bit
Speed	8MHz
Connectivity	I <sup>2</sup> C, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	48
Program Memory Size	60KB (60K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3.8V ~ 5.5V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	-
Purchase URL	https://www.e-xfl.com/product-detail/stmicroelectronics/st72f321r9tc

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Address	Block	Register Label	Register Name	Reset Status	Remarks			
0058h to 006Fh		Reserved Area (24 Bytes)						
0070h 0071h 0072h	ADC	ADCCSR ADCDRH ADCDRL	Control/Status Register Data High Register Data Low Register	00h 00h 00h	R/W Read Only Read Only			
0073h 0074h 0075h 0076h 0077h 0078h 0079h 007Ah 007Bh 007Ch 007Dh	PWM ART	PWMDCR3 PWMDCR1 PWMDCR0 PWMCR ARTCSR ARTCAR ARTARR ARTICCSR ARTICCSR ARTICR1 ARTICR2	PWM AR Timer Duty Cycle Register 3 PWM AR Timer Duty Cycle Register 2 PWM AR Timer Duty Cycle Register 1 PWM AR Timer Duty Cycle Register 0 PWM AR Timer Control Register 0 Auto-Reload Timer Control/Status Register Auto-Reload Timer Counter Access Register Auto-Reload Timer Auto-Reload Register AR Timer Input Capture Control/Status Reg. AR Timer Input Capture Register 1 AR Timer Input Capture Register 1	00h 00h 00h 00h 00h 00h 00h 00h 00h	R/W R/W R/W R/W R/W R/W R/W R/W Read Only Read Only			
007Eh 007Fh	Reserved Area (2 Bytes)							

Legend: x=undefined, R/W=read/write

# Notes:

- 1. The contents of the I/O port DR registers are readable only in output configuration. In input configuration, the values of the I/O pins are returned instead of the DR register contents.
- 2. The bits associated with unavailable pins must always keep their reset value.

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# I/O PORTS (Cont'd)

Table 13. I/O Port Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
	t Value ort registers	0	0	0	0	0	0	0	0
0000h	PADR								
0001h	PADDR	MSB							LSB
0002h	PAOR								
0003h	PBDR								
0004h	PBDDR	MSB							LSB
0005h	PBOR								
0006h	PCDR								
0007h	PCDDR	MSB							LSB
0008h	PCOR								
0009h	PDDR								
000Ah	PDDDR	MSB							LSB
000Bh	PDOR								
000Ch	PEDR								
000Dh	PEDDR	MSB							LSB
000Eh	PEOR								
000Fh	PFDR								
0010h	PFDDR	MSB							LSB
0011h	PFOR								

#### **Related Documentation**

AN 970: SPI Communication between ST7 and EEPROM

AN1045: S/W implementation of I2C bus master

AN1048: Software LCD driver

# Table 14. Watchdog Timer Register Map and Reset Values

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
000Ab	WDGCR	WDGA	T6	T5	T4	T3	T2	T1	T0
002Ah	Reset Value	0	1	1	1	1	1	1	1

Figure 46. Input Capture Block Diagram

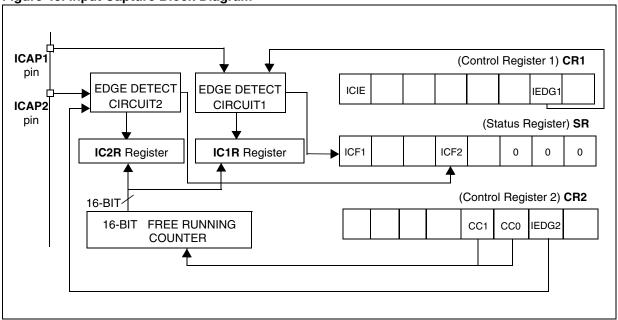
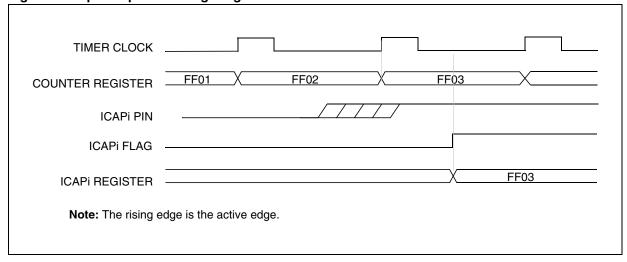


Figure 47. Input Capture Timing Diagram



#### 10.4.3.5 One Pulse Mode

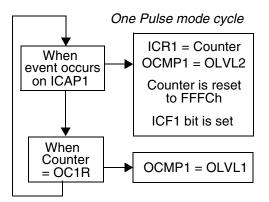
One Pulse mode enables the generation of a pulse when an external event occurs. This mode is selected via the OPM bit in the CR2 register.

The One Pulse mode uses the Input Capture1 function and the Output Compare1 function.

#### **Procedure:**

To use One Pulse mode:

- Load the OC1R register with the value corresponding to the length of the pulse (see the formula in the opposite column).
- 2. Select the following in the CR1 register:
  - Using the OLVL1 bit, select the level to be applied to the OCMP1 pin after the pulse.
  - Using the OLVL2 bit, select the level to be applied to the OCMP1 pin during the pulse.
  - Select the edge of the active transition on the ICAP1 pin with the IEDG1 bit (the ICAP1 pin must be configured as floating input).
- 3. Select the following in the CR2 register:
  - Set the OC1E bit, the OCMP1 pin is then dedicated to the Output Compare 1 function.
  - Set the OPM bit.
  - Select the timer clock CC[1:0] (see Table 1).



Then, on a valid event on the ICAP1 pin, the counter is initialized to FFFCh and OLVL2 bit is loaded on the OCMP1 pin, the ICF1 bit is set and the value FFFDh is loaded in the IC1R register.

Because the ICF1 bit is set when an active edge occurs, an interrupt can be generated if the ICIE bit is set.

Clearing the Input Capture interrupt request (that is, clearing the ICF*i* bit) is done in two steps:

- 1. Reading the SR register while the ICF*i* bit is set.
- 2. An access (read or write) to the ICiLR register.

The OC1R register value required for a specific timing application can be calculated using the following formula:

OCiR Value = 
$$\frac{t \cdot f_{CPU}}{PRESC} - 5$$

Where:

t = Pulse period (in seconds)

 $f_{CPU} = CPU$  clock frequency (in hertz)

PRESC = Timer prescaler factor (2, 4 or 8 depending on the CC[1:0] bits, see Table 1)

If the timer clock is an external clock the formula is:

$$OCiR = t * f_{FXT} - 5$$

Where:

t = Pulse period (in seconds)

f<sub>EXT</sub> = External timer clock frequency (in hertz)

When the value of the counter is equal to the value of the contents of the OC1R register, the OLVL1 bit is output on the OCMP1 pin, (See Figure 10).

#### Notes:

- The OCF1 bit cannot be set by hardware in One Pulse mode but the OCF2 bit can generate an Output Compare interrupt.
- 2. When the Pulse Width Modulation (PWM) and One Pulse mode (OPM) bits are both set, the PWM mode is the only active one.
- 3. If OLVL1 = OLVL2 a continuous signal will be seen on the OCMP1 pin.
- 4. The ICAP1 pin can not be used to perform input capture. The ICAP2 pin can be used to perform input capture (ICF2 can be set and IC2R can be loaded) but the user must take care that the counter is reset each time a valid edge occurs on the ICAP1 pin and ICF1 can also generates interrupt if ICIE is set.
- 5. When One Pulse mode is used OC1R is dedicated to this mode. Nevertheless OC2R and OCF2 can be used to indicate a period of time has been elapsed but cannot generate an output waveform because the level OLVL2 is dedicated to the One Pulse mode.

#### 10.4.7 Register Description

Each Timer is associated with three control and status registers, and with six pairs of data registers (16-bit values) relating to the two input captures, the two output compares, the counter and the alternate counter.

# **CONTROL REGISTER 1 (CR1)**

Read/Write

Reset Value: 0000 0000 (00h)

7							0
ICIE	OCIE	TOIE	FOLV2	FOLV1	OLVL2	IEDG1	OLVL1

Bit 7 = ICIE Input Capture Interrupt Enable.

0: Interrupt is inhibited.

1: A timer interrupt is generated whenever the ICF1 or ICF2 bit of the SR register is set.

Bit 6 = **OCIE** *Output Compare Interrupt Enable.* 0: Interrupt is inhibited.

1: A timer interrupt is generated whenever the OCF1 or OCF2 bit of the SR register is set.

Bit 5 = **TOIE** *Timer Overflow Interrupt Enable.* 

0: Interrupt is inhibited.

1: A timer interrupt is enabled whenever the TOF bit of the SR register is set.

Bit 4 = FOLV2 Forced Output Compare 2.

This bit is set and cleared by software.

0: No effect on the OCMP2 pin.

1: Forces the OLVL2 bit to be copied to the OCMP2 pin, if the OC2E bit is set and even if there is no successful comparison.

Bit 3 = FOLV1 Forced Output Compare 1.

This bit is set and cleared by software.

0: No effect on the OCMP1 pin.

1: Forces OLVL1 to be copied to the OCMP1 pin, if the OC1E bit is set and even if there is no successful comparison.

#### Bit 2 = OLVL2 Output Level 2.

This bit is copied to the OCMP2 pin whenever a successful comparison occurs with the OC2R register and OCxE is set in the CR2 register. This value is copied to the OCMP1 pin in One Pulse mode and Pulse Width Modulation mode.

Bit 1 = **IEDG1** Input Edge 1.

This bit determines which type of level transition on the ICAP1 pin will trigger the capture.

0: A falling edge triggers the capture.

1: A rising edge triggers the capture.

#### Bit 0 = **OLVL1** Output Level 1.

The OLVL1 bit is copied to the OCMP1 pin whenever a successful comparison occurs with the OC1R register and the OC1E bit is set in the CR2 register.

#### **CONTROL/STATUS REGISTER (CSR)**

Read/Write (bits 7:3 read only)
Reset Value: xxxx x0xx (xxh)

7							0
ICF1	OCF1	TOF	ICF2	OCF2	TIMD	0	0

#### Bit 7 = ICF1 Input Capture Flag 1.

0: No input capture (reset value).

1: An input capture has occurred on the ICAP1 pin or the counter has reached the OC2R value in PWM mode. To clear this bit, first read the SR register, then read or write the low byte of the IC1R (IC1LR) register.

#### Bit 6 = **OCF1** Output Compare Flag 1.

0: No match (reset value).

1: The content of the free running counter has matched the content of the OC1R register. To clear this bit, first read the SR register, then read or write the low byte of the OC1R (OC1LR) register.

#### Bit 5 = **TOF** Timer Overflow Flag.

0: No timer overflow (reset value).

1: The free running counter rolled over from FFFFh to 0000h. To clear this bit, first read the SR register, then read or write the low byte of the CR (CLR) register.

**Note:** Reading or writing the ACLR register does not clear TOF.

### Bit 4 = ICF2 Input Capture Flag 2.

0: No input capture (reset value).

1: An input capture has occurred on the ICAP2 pin. To clear this bit, first read the SR register, then read or write the low byte of the IC2R (IC2LR) register.

#### Bit 3 = **OCF2** Output Compare Flag 2.

0: No match (reset value).

 The content of the free running counter has matched the content of the OC2R register. To clear this bit, first read the SR register, then read or write the low byte of the OC2R (OC2LR) register.

#### Bit 2 = **TIMD** Timer disable.

This bit is set and cleared by software. When set, it freezes the timer prescaler and counter and disabled the output functions (OCMP1 and OCMP2 pins) to reduce power consumption. Access to the timer registers is still available, allowing the timer configuration to be changed, or the counter reset, while it is disabled.

0: Timer enabled

1: Timer prescaler, counter and outputs disabled

Bits 1:0 = Reserved, must be kept cleared.

# SERIAL COMMUNICATIONS INTERFACE (Cont'd) 10.6.4.9 Clock Deviation Causes

The causes which contribute to the total deviation are:

- D<sub>TRA</sub>: Deviation due to transmitter error (Local oscillator error of the transmitter or the transmitter is transmitting at a different baud rate).
- D<sub>QUANT</sub>: Error due to the baud rate quantization of the receiver.
- D<sub>RFC</sub>: Deviation of the local oscillator of the receiver: This deviation can occur during the reception of one complete SCI message assuming that the deviation has been compensated at the beginning of the message.
- D<sub>TCI</sub>: Deviation due to the transmission line (generally due to the transceivers)

All the deviations of the system should be added and compared to the SCI clock tolerance:

 $D_{TRA} + D_{QUANT} + D_{REC} + D_{TCL} < 3.75\%$ 

#### 10.6.4.10 Noise Error Causes

See also description of Noise error in Section 0.1.4.3.

#### Start bit

The noise flag (NF) is set during start bit reception if one of the following conditions occurs:

- 1. A valid falling edge is not detected. A falling edge is considered to be valid if the 3 consecutive samples before the falling edge occurs are detected as '1' and, after the falling edge occurs, during the sampling of the 16 samples, if one of the samples numbered 3, 5 or 7 is detected as a "1".
- 2. During sampling of the 16 samples, if one of the samples numbered 8, 9 or 10 is detected as a

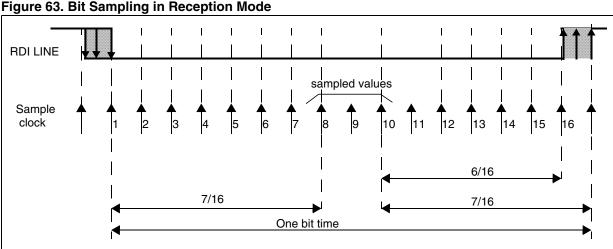
Therefore, a valid Start Bit must satisfy both the above conditions to prevent the Noise Flag getting set.

#### **Data Bits**

The noise flag (NF) is set during normal data bit reception if the following condition occurs:

- During the sampling of 16 samples, if all three samples numbered 8, 9 and 10 are not the same. The majority of the 8th, 9th and 10th samples is considered as the bit value.

Therefore, a valid Data Bit must have samples 8, 9 and 10 at the same value to prevent the Noise Flag getting set.



# I<sup>2</sup>C BUS INTERFACE (Cont'd) I<sup>2</sup>C STATUS REGISTER 1 (SR1)

Read Only

Reset Value: 0000 0000 (00h)

7							0
EVF	ADD10	TRA	BUSY	BTF	ADSL	M/SL	SB

#### Bit 7 = **EVF** Event flag.

This bit is set by hardware as soon as an event occurs. It is cleared by software reading SR2 register in case of error event or as described in Figure 66. It is also cleared by hardware when the interface is disabled (PE=0).

0: No event

- 1: One of the following events has occurred:
  - BTF=1 (Byte received or transmitted)
  - ADSL=1 (Address matched in Slave mode while ACK=1)
  - SB=1 (Start condition generated in Master mode)
  - AF=1 (No acknowledge received after byte transmission)
  - STOPF=1 (Stop condition detected in Slave mode)
  - ARLO=1 (Arbitration lost in Master mode)
  - BERR=1 (Bus error, misplaced Start or Stop condition detected)
  - ADD10=1 (Master has sent header byte)
  - Address byte successfully transmitted in Master mode.

Bit 6 = **ADD10** 10-bit addressing in Master mode. This bit is set by hardware when the master has sent the first byte in 10-bit address mode. It is cleared by software reading SR2 register followed by a write in the DR register of the second address byte. It is also cleared by hardware when the peripheral is disabled (PE=0).

0: No ADD10 event occurred.

1: Master has sent first address byte (header)

#### Bit 5 = **TRA** *Transmitter/Receiver*.

When BTF is set, TRA=1 if a data byte has been transmitted. It is cleared automatically when BTF is cleared. It is also cleared by hardware after detection of Stop condition (STOPF=1), loss of bus arbitration (ARLO=1) or when the interface is disabled (PE=0).

0: Data byte received (if BTF=1)

#### 1: Data byte transmitted

#### Bit 4 = BUSY Bus busy.

This bit is set by hardware on detection of a Start condition and cleared by hardware on detection of a Stop condition. It indicates a communication in progress on the bus. The BUSY flag of the I2CSR1 register is cleared if a Bus Error occurs.

- 0: No communication on the bus
- 1: Communication ongoing on the bus Note:
- The BUSY flag is NOT updated when the interface is disabled (PE=0). This can have consequences when operating in Multimaster mode; i.e. a second active I<sup>2</sup>C master commencing a transfer with an unset BUSY bit can cause a conflict resulting in lost data. A software workaround consists of checking that the I<sup>2</sup>C is not busy before enabling the I<sup>2</sup>C Multimaster cell.

#### Bit 3 = **BTF** Byte transfer finished.

This bit is set by hardware as soon as a byte is correctly received or transmitted with interrupt generation if ITE=1. It is cleared by software reading SR1 register followed by a read or write of DR register. It is also cleared by hardware when the interface is disabled (PE=0).

- Following a byte transmission, this bit is set after reception of the acknowledge clock pulse. In case an address byte is sent, this bit is set only after the EV6 event (See Figure 66). BTF is cleared by reading SR1 register followed by writing the next byte in DR register.
- Following a byte reception, this bit is set after transmission of the acknowledge clock pulse if ACK=1. BTF is cleared by reading SR1 register followed by reading the byte from DR register.

The SCL line is held low while BTF=1.

- 0: Byte transfer not done
- 1: Byte transfer succeeded

Bit 2 = **ADSL** Address matched (Slave mode). This bit is set by hardware as soon as the received slave address matched with the OAR register content or a general call is recognized. An interrupt is generated if ITE=1. It is cleared by software reading SR1 register or by hardware when the interface is disabled (PE=0).

The SCL line is held low while ADSL=1.

- 0: Address mismatched or not received
- 1: Received address matched



# 10-BIT A/D CONVERTER (Cont'd)

# **Table 25. ADC Register Map and Reset Values**

Address (Hex.)	Register Label	7	6	5	4	3	2	1	0
0070h	ADCCSR Reset Value	EOC 0	SPEED 0	ADON 0	0	CH3 0	CH2 0	CH1 0	CH0 0
0071h	ADCDRH Reset Value	D9 0	D8 0	D7 0	D6 0	D5 0	D4 0	D3 0	D2 0
0072h	ADCDRL Reset Value	0	0	0	0	0	0	D1 0	D0 0

#### **INSTRUCTION SET OVERVIEW** (Cont'd)

#### 11.1.6 Indirect Indexed (Short, Long)

This is a combination of indirect and short indexed addressing modes. The operand is referenced by its memory address, which is defined by the unsigned addition of an index register value (X or Y) with a pointer value located in memory. The pointer address follows the opcode.

The indirect indexed addressing mode consists of two submodes:

#### Indirect Indexed (Short)

The pointer address is a byte, the pointer size is a byte, thus allowing 00 - 1FE addressing space, and requires 1 byte after the opcode.

#### Indirect Indexed (Long)

The pointer address is a byte, the pointer size is a word, thus allowing 64 Kbyte addressing space, and requires 1 byte after the opcode.

Table 27. Instructions Supporting Direct, Indexed, Indirect and Indirect Indexed Addressing Modes

Long and Short Instructions	Function
LD	Load
CP	Compare
AND, OR, XOR	Logical Operations
ADC, ADD, SUB, SBC	Arithmetic Additions/Sub- stractions operations
BCP	Bit Compare

<b>Short Instructions Only</b>	Function
CLR	Clear
INC, DEC	Increment/Decrement
TNZ	Test Negative or Zero
CPL, NEG	1 or 2 Complement
BSET, BRES	Bit Operations
BTJT, BTJF	Bit Test and Jump Operations
SLL, SRL, SRA, RLC, RRC	Shift and Rotate Operations
SWAP	Swap Nibbles
CALL, JP	Call or Jump subroutine

# 11.1.7 Relative mode (Direct, Indirect)

This addressing mode is used to modify the PC register value, by adding an 8-bit signed offset to it.

Available Relative Direct/Indirect Instructions	Function
JRxx	Conditional Jump
CALLR	Call Relative

The relative addressing mode consists of two submodes:

# **Relative (Direct)**

The offset is following the opcode.

#### Relative (Indirect)

The offset is defined in memory, which address follows the opcode.

#### 12.4 SUPPLY CURRENT CHARACTERISTICS

The following current consumption specified for the ST7 functional operating modes over temperature range does not take into account the clock source current consumption. To get the total device consumption, the two current values must be added (except for HALT mode for which the clock is stopped).

#### 12.4.1 CURRENT CONSUMPTION

Symbol	Parameter	Conditions	Flash Devices		ROM Devices		Hnit	
Symbol	Parameter	Conditions	Тур	Max 1)	Тур	Max 1)	Jiiit	
I <sub>DD</sub>	Supply current in RUN mode <sup>2)</sup>	$\begin{array}{l} f_{OSC} = 2 \text{MHz},  f_{CPU} = 1 \text{MHz} \\ f_{OSC} = 4 \text{MHz},  f_{CPU} = 2 \text{MHz} \\ f_{OSC} = 8 \text{MHz},  f_{CPU} = 4 \text{MHz} \\ f_{OSC} = 16 \text{MHz},  f_{CPU} = 8 \text{MHz} \end{array}$	1.3 2.0 3.6 7.1	3.0 5.0 8.0 15.0	1.3 2.0 3.6 7.1	2.0 3.0 5.0 10.0	mA	
	Supply current in SLOW mode <sup>2)</sup>	$\begin{array}{l} f_{OSC} {=} 2 \text{MHz}, f_{CPU} {=} 62.5 \text{kHz} \\ f_{OSC} {=} 4 \text{MHz}, f_{CPU} {=} 125 \text{kHz} \\ f_{OSC} {=} 8 \text{MHz}, f_{CPU} {=} 250 \text{kHz} \\ f_{OSC} {=} 16 \text{MHz}, f_{CPU} {=} 500 \text{kHz} \end{array}$	600 700 800 1100	2700 3000 3600 4000	600 700 800 1100	1800 2100 2400 3000	μА	
	Supply current in WAIT mode <sup>2)</sup>	$\begin{array}{l} f_{OSC} = 2 \text{MHz},  f_{CPU} = 1 \text{MHz} \\ f_{OSC} = 4 \text{MHz},  f_{CPU} = 2 \text{MHz} \\ f_{OSC} = 8 \text{MHz},  f_{CPU} = 4 \text{MHz} \\ f_{OSC} = 16 \text{MHz},  f_{CPU} = 8 \text{MHz} \end{array}$	1.0 1.5 2.5 4.5	3.0 4.0 5.0 7.0	1.0 1.5 2.5 4.5	1.3 2.0 3.3 6.0	mA	
	Supply current in SLOW WAIT mode <sup>2)</sup>	$\begin{array}{l} f_{OSC} {=} 2 \text{MHz}, f_{CPU} {=} 62.5 \text{kHz} \\ f_{OSC} {=} 4 \text{MHz}, f_{CPU} {=} 125 \text{kHz} \\ f_{OSC} {=} 8 \text{MHz}, f_{CPU} {=} 250 \text{kHz} \\ f_{OSC} {=} 16 \text{MHz}, f_{CPU} {=} 500 \text{kHz} \end{array}$	580 650 770 1050	1200 1300 1800 2000	70 100 200 350	200 300 600 1200	μА	
	Supply current in HALT mode 3)	-40°C≤T <sub>A</sub> ≤+85°C	<1	10	<1	10	μΑ	
		-40°C≤T <sub>A</sub> ≤+125°C	<1	50	<1	50		
I <sub>DD</sub>	Supply current in ACTIVE-HALT mode 4)	$f_{OSC}$ =2MHz $f_{OSC}$ =4MHz $f_{OSC}$ =8MHz $f_{OSC}$ =16MHz	80 160 325 650	No max. guaran- teed	80 160 325 650	No max. guar- anteed	μΑ	

#### Notes:

- 1. Data based on characterization results, tested in production at V<sub>DD</sub> max. and f<sub>CPU</sub> max.
- 2. Measurements are done in the following conditions:
- Program executed from RAM, CPU running with RAM access. The increase in consumption when executing from Flash is 50%.
- All I/O pins in input mode with a static value at V<sub>DD</sub> or V<sub>SS</sub> (no load)
- All peripherals in reset state.
- LVD disabled.
- Clock input (OSC1) driven by external square wave.
- In SLOW and SLOW WAIT mode,  $f_{CPU}$  is based on  $f_{OSC}$  divided by 32.
- To obtain the total current consumption of the device, add the clock source (Section 12.4.2) and the peripheral power consumption (Section 12.4.3).
- 3. All I/O pins in push-pull 0 mode (when applicable) with a static value at  $V_{DD}$  or VSS (no load), LVD disabled. Data based on characterization results, tested in production at  $V_{DD}$  max. and  $f_{CPU}$  max.
- 4. Data based on characterisation results, not tested in production. All I/O pins in push-pull 0 mode (when applicable) with a static value at V<sub>DD</sub> or V<sub>SS</sub> (no load); clock input (OSC1) driven by external square wave, LVD disabled. To obtain the total current consumption of the device, add the clock source consumption (Section 12.4.2).

#### 12.6 MEMORY CHARACTERISTICS

# 12.6.1 RAM and Hardware Registers

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
$V_{RM}$	Data retention mode 1)	HALT mode (or RESET)	1.6			V

#### 12.6.2 FLASH Memory

DUAL VOLTAGE HDFLASH MEMORY									
Symbol	Parameter	Conditions	Min <sup>2)</sup>	Тур	Max 2)	Unit			
ŧ	Operating frequency	Read mode	0		8	MHz			
† <sub>CPU</sub>	Operating frequency	Write / Erase mode	1		8				
V <sub>PP</sub>	Programming voltage 3)	$4.5V \le V_{DD} \le 5.5V$	11.4		12.6	V			
		RUN mode (f <sub>CPU</sub> = 4MHz)			3	A			
I <sub>DD</sub>	Supply current <sup>4)</sup>	Write / Erase		0		- mA			
		Power down mode / HALT		1	10	μΑ			
ı	V <sub>PP</sub> current <sup>4)</sup>	Read (V <sub>PP</sub> =12V)			200				
I <sub>PP</sub>	VPP Current	Write / Erase			30	mA			
t <sub>VPP</sub>	Internal V <sub>PP</sub> stabilization time			10		μs			
		T <sub>A</sub> =85°C	40						
t <sub>RET</sub>	Data retention	T <sub>A</sub> =105°C	15			years			
		T <sub>A</sub> =125°C	7						
N	Write erase cycles	T <sub>A</sub> = 55°C	1000			cycles			
N <sub>RW</sub>	Wille crase cycles	T <sub>A</sub> = 85°C	100			cycles			
T <sub>PROG</sub> T <sub>ERASE</sub>	Programming or erasing temperature range		-40	25	85	°C			

#### Notes:

- 1. Minimum  $V_{DD}$  supply voltage without losing data stored in RAM (in HALT mode or under RESET) or in hardware registers (only in HALT mode). Not tested in production.
- 2. Data based on characterization results, not tested in production.
- 3. V<sub>PP</sub> must be applied only during the programming or erasing operation and not permanently for reliability reasons.
- 4. Data based on simulation results, not tested in production.

Warning: Do not connect 12V to  $V_{PP}$  before  $V_{DD}$  is powered on, as this may damage the device.

#### 12.9 CONTROL PIN CHARACTERISTICS

# 12.9.1 Asynchronous RESET Pin

Subject to general operating conditions for V<sub>DD</sub>, f<sub>CPU</sub>, and T<sub>A</sub> unless otherwise specified.

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
V <sub>IL</sub>	Input low level voltage 1)					0.16xV <sub>DD</sub>	V
V <sub>IH</sub>	Input high level voltage 1)			$0.85 \text{xV}_{\text{DD}}$			v
V <sub>hys</sub>	Schmitt trigger voltage hysteresis <sup>2)</sup>				2.5		٧
V <sub>OL</sub>	Output low level voltage 3)	V <sub>DD</sub> =5V	I <sub>IO</sub> =+2mA		0.2	0.5	V
I <sub>IO</sub>	Input current on RESET pin				2		mA
R <sub>ON</sub>	Weak pull-up equivalent resistor			20	30	120	kΩ
t <sub>w(RSTL)out</sub>			oplied on oulse	0		42 <sup>6)</sup>	μs
, ,		Internal reset sources		20	30	42 <sup>6)</sup>	μS
t <sub>h(RSTL)in</sub>	External reset pulse hold time 4)			2.5			μS
t <sub>g(RSTL)in</sub>	Filtered glitch duration <sup>5)</sup>				200		ns

#### Notes:

- 1. Data based on characterization results, not tested in production.
- 2. Hysteresis voltage between Schmitt trigger switching levels.
- 3. The  $I_{IO}$  current sunk must always respect the absolute maximum rating specified in Section 12.2.2 and the sum of  $I_{IO}$  (I/O ports and control pins) must not exceed  $I_{VSS}$ .
- 4. To guarantee the reset of the device, a minimum pulse has to be applied to the  $\overline{\text{RESET}}$  pin. All short pulses applied on the RESET pin with a duration below  $t_{h(RSTL)in}$  can be ignored.
- 5. The reset network (the resistor and two capacitors) protects the device against parasitic resets, especially in noisy environments.
- 6. Data guaranteed by design, not tested in production.

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#### **CONTROL PIN CHARACTERISTICS (Cont'd)**

Figure 89. RESET pin protection when LVD is enabled. 1)2)3)4)

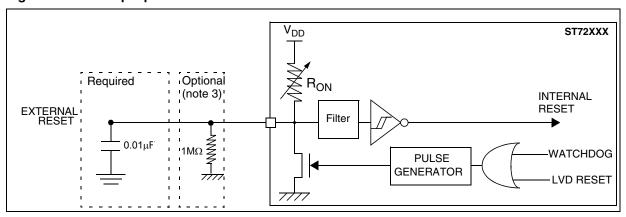
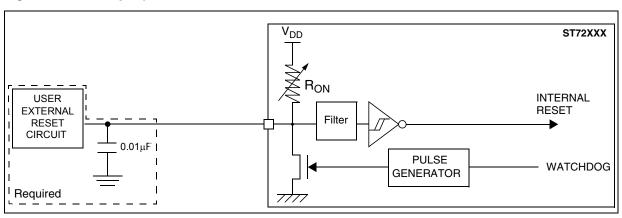


Figure 90. RESET pin protection when LVD is disabled. 1)



#### Note 1:

- The reset network protects the device against parasitic resets.
- The output of the external reset circuit must have an open-drain output to drive the ST7 reset pad. Otherwise the
  device can be damaged when the ST7 generates an internal reset (LVD or watchdog).
- Whatever the reset source is (internal or external), the user must ensure that the level on the RESET pin can go below the V<sub>IL</sub> max. level specified in section 12.9.1 on page 159. Otherwise the reset will not be taken into account internally.
- Because the reset circuit is designed to allow the internal RESET to be output in the RESET pin, the user must ensure that the current sunk on the RESET pin is less than the absolute maximum value specified for I<sub>INJ(RESET)</sub> in section 12.2.2 on page 139.

**Note 2:** When the LVD is enabled, it is recommended not to connect a pull-up resistor or capacitor. A 10nF pull-down capacitor is required to filter noise on the reset line.

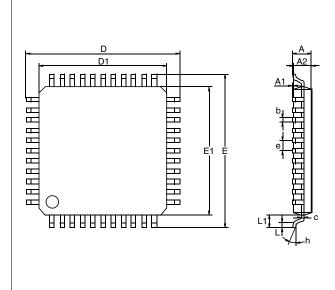
**Note 3:** In case a capacitive power supply is used, it is recommended to connect a  $1M\Omega$  pull-down resistor to the  $\overline{RESET}$  pin to discharge any residual voltage induced by the capacitive effect of the power supply (this will add  $5\mu A$  to the power consumption of the MCU).

Note 4: Tips when using the LVD:

- 1. Check that all recommendations related to reset circuit have been applied (see notes above).
- 2. Check that the power supply is properly decoupled (100nF + 10μF close to the MCU). Refer to AN1709 and AN2017. If this cannot be done, it is recommended to put a 100nF + 1MΩ pull-down on the RESET pin.
- 3. The capacitors connected on the RESET pin and also the power supply are key to avoid any start-up marginality.
   In most cases, steps 1 and 2 above are sufficient for a robust solution. Otherwise: replace 10nF pull-down on the RESET pin with a 5μF to 20μF capacitor.

# PACKAGE MECHANICAL DATA (Cont'd)

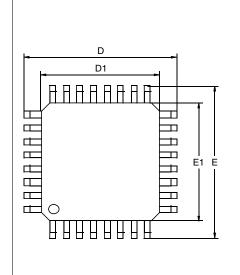
Figure 103. 44-Pin Low Profile Quad Flat Package

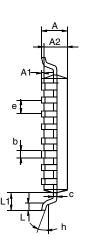


D:	mm			inches <sup>1)</sup>				
Dim.	Min	Тур	Max	Min	Тур	Max		
Α			1.60			0.0630		
<b>A</b> 1	0.05		0.15	0.0020		0.0059		
A2	1.35	1.40	1.45	0.0531	0.0551	0.0571		
b	0.30	0.37	0.45	0.0118	0.0146	0.0177		
С	0.09		0.20	0.0035		0.0079		
D		12.00			0.4724			
D1		10.00			0.3937			
Е		12.00			0.4724			
E1		10.00			0.3937			
е		0.80			0.0315			
θ	0°	3.5°	7°	0°	3.5°	7°		
L	0.45	0.60	0.75	0.0177	0.0236	0.0295		
L1		1.00			0.0394			
	Number of Pins							
Note 1	44 Values in inches are converted from mm							

Note 1. Values in inches are converted from mm and rounded to 4 decimal digits.

Figure 104. 32-Pin Low Profile Quad Flat Package



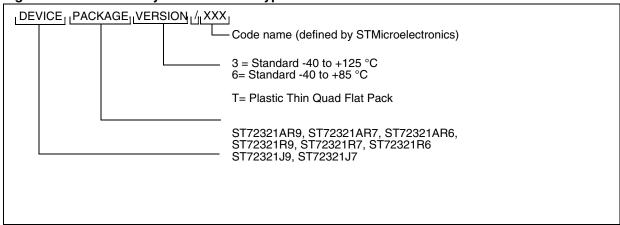


Dim.		mm		inches <sup>1)</sup>			
Dilli.	Min	Тур	Max	Min	Тур	Max	
A			1.60			0.0630	
<b>A</b> 1	0.05		0.15	0.0020		0.0059	
A2	1.35	1.40	1.45	0.0531	0.0551	0.0571	
b	0.30	0.37	0.45	0.0118	0.0146	0.0177	
O	0.09		0.20	0.0035		0.0079	
D		9.00			0.3543		
D1		7.00			0.2756		
Е		9.00			0.3543		
E1		7.00			0.2756		
е		0.80			0.0315		
θ	0°	3.5°	7°	0°	3.5°	7°	
L	0.45	0.60	0.75	0.0177	0.0236	0.0295	
L1		1.00			0.0394		
	Number of Pins						
N	32						

Note 1. Values in inches are converted from mm and rounded to 4 decimal digits.

## ST723251 DEVICE CONFIGURATION AND ORDERING INFORMATION (Cont'd)

Figure 106. ROM Factory Coded Device Types



#### **15 KNOWN LIMITATIONS**

#### 15.1 ALL FLASH AND ROM DEVICES

#### 15.1.1 External RC option

The External RC clock source option described in previous datasheet revisions is no longer supported and has been removed from this specification.

#### 15.1.2 Safe Connection of OSC1/OSC2 Pins

The OSC1 and/or OSC2 pins must not be left unconnected otherwise the ST7 main oscillator may start and, in this configuration, could generate an f<sub>OSC</sub> clock frequency in excess of the allowed maximum (>16MHz.), putting the ST7 in an unsafe/undefined state. Refer to section 6.2 on page 25.

#### 15.1.3 Reset pin protection with LVD Enabled

As mentioned in note 2 below Figure 89 on page 160, when the LVD is enabled, it is recommended not to connect a pull-up resistor or capacitor. A 10nF pull-down capacitor is required to filter noise on the reset line.

#### 15.1.4 Unexpected Reset Fetch

If an interrupt request occurs while a "POP CC" instruction is executed, the interrupt controller does not recognise the source of the interrupt and, by default, passes the RESET vector address to the CPU.

#### Workaround

To solve this issue, a "POP CC" instruction must always be preceded by a "SIM" instruction.

#### 15.1.5 External interrupt missed

To avoid any risk if generating a parasitic interrupt, the edge detector is automatically disabled for one clock cycle during an access to either DDR and OR. Any input signal edge during this period will not be detected and will not generate an interrupt.

This case can typically occur if the application refreshes the port configuration registers at intervals during runtime.

#### Workaround

The workaround is based on software checking the level on the interrupt pin before and after writing to the PxOR or PxDDR registers. If there is a level change (depending on the sensitivity programmed for this pin) the interrupt routine is invoked using the call instruction with three extra PUSH instructions before executing the interrupt routine (this is to make the call compatible with the IRET instruction at the end of the interrupt service routine).

But detection of the level change does not make sure that edge occurs during the critical 1 cycle duration and the interrupt has been missed. This may lead to occurrence of same interrupt twice (one hardware and another with software call).

To avoid this, a semaphore is set to '1' before checking the level change. The semaphore is changed to level '0' inside the interrupt routine. When a level change is detected, the semaphore status is checked and if it is '1' this means that the last interrupt has been missed. In this case, the interrupt routine is invoked with the call instruction.

There is another possible case i.e. if writing to PxOR or PxDDR is done with global interrupts disabled (interrupt mask bit set). In this case, the semaphore is changed to '1' when the level change is detected. Detecting a missed interrupt is done after the global interrupts are enabled (interrupt mask bit reset) and by checking the status of the semaphore. If it is '1' this means that the last interrupt was missed and the interrupt routine is invoked with the call instruction.

To implement the workaround, the following software sequence is to be followed for writing into the PxOR/PxDDR registers. The example is for for Port PF1 with falling edge interrupt sensitivity. The software sequence is given for both cases (global interrupt disabled/enabled).

**Case 1:** Writing to PxOR or PxDDR with Global Interrupts Enabled:

LD A,#01

LD sema,A ; set the semaphore to '1'

LD A,PFDR AND A,#02

LD X,A; store the level before writing to

PxOR/PxDDR

LD PFDDR,A; Write to PFDDR

LD A,#\$ff

LD A,#\$90

LD PFOR,A ; Write to PFOR

LD A,PFDR AND A,#02

LD Y,A; store the level after writing to

PxOR/PxDDR

LD A,X ; check for falling edge

cp A,#02 jrne OUT